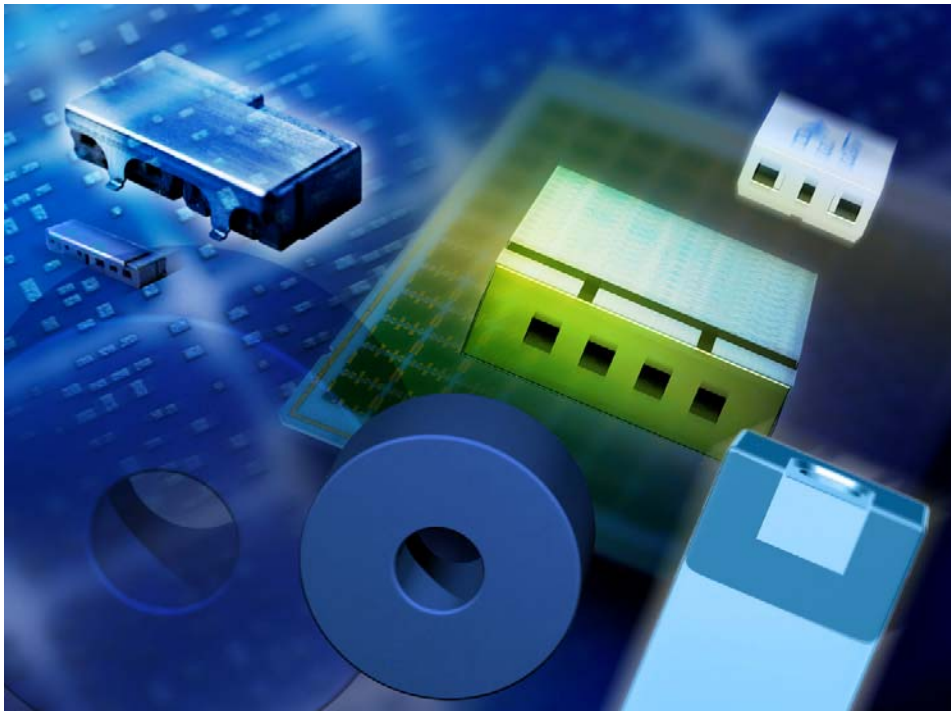


Data Sheet



Application

- RF filter for WLL (Wireless Local Loop)

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3\text{-CaTiO}_3$ ($\epsilon_r = 21 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization
- ESD insensitivity and ESD protecting due to filter characteristics

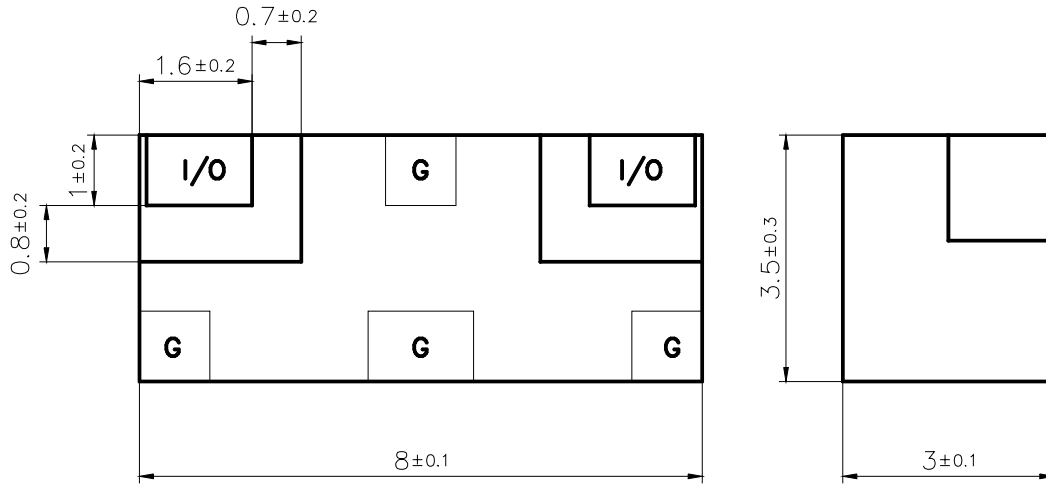
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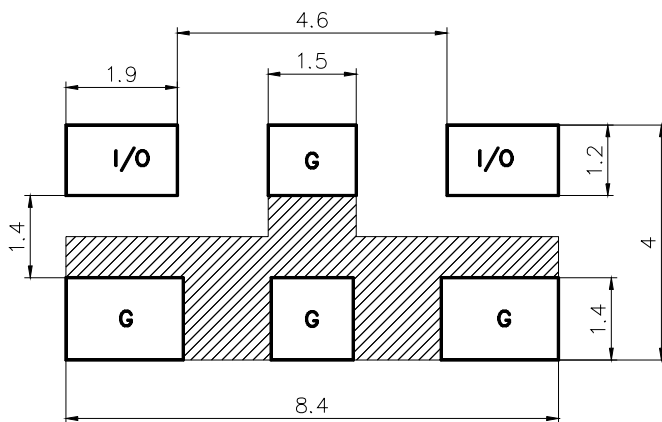
Data Sheet

Component drawing



View from below onto the solder terminals and view from beside

Recommended Footprint



solder pads

I/O

connected to lines with an impedance of 50 Ohm

Standard condition

FR4 material
 permittivity : 4.4
 preferred thickness : 0.3
 Vias: Ø0.3mm / mm²
 For other thickness
 correlation might be necessary

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Data Sheet

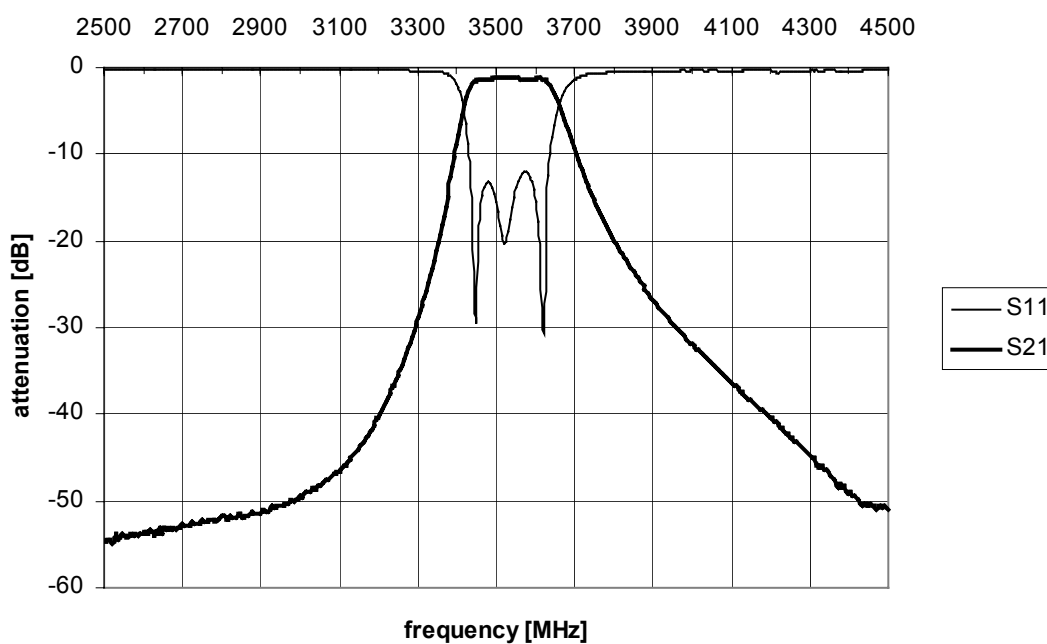
Characteristics

		min.	typ.	max.	
Center frequency	f_C	-	3550.0	-	MHz
Insertion loss	α_{IL}		0.9	1.2	dB
Passband	B	120			MHz
Amplitude ripple (peak - peak) at any 10MHz BW	$\Delta\alpha$			0.4	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
	at 2588 to 2688 MHz	45	48		dB
	at 3900 to 4200 MHz	20	26		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{Op}	-40 / + 85	$^{\circ}C$

Typical passband characteristic



Data Sheet

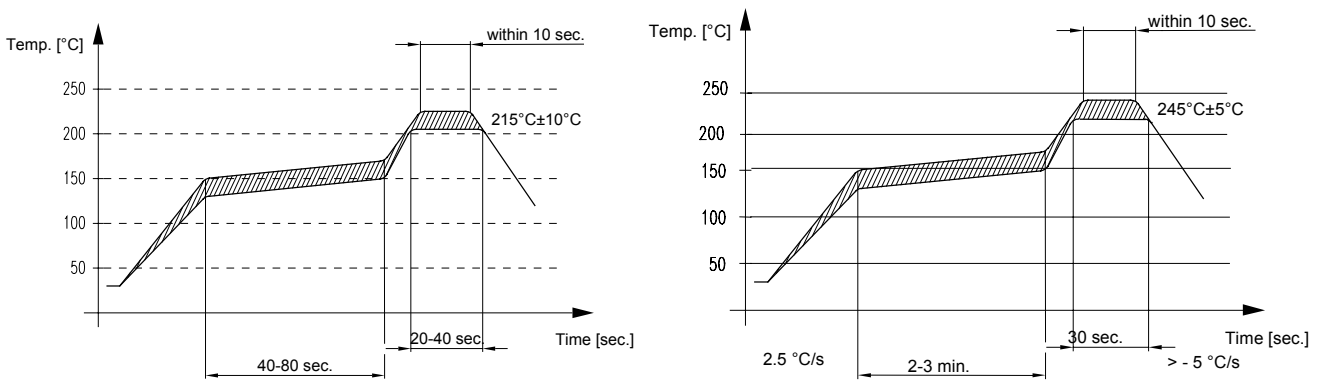
Processing information

- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

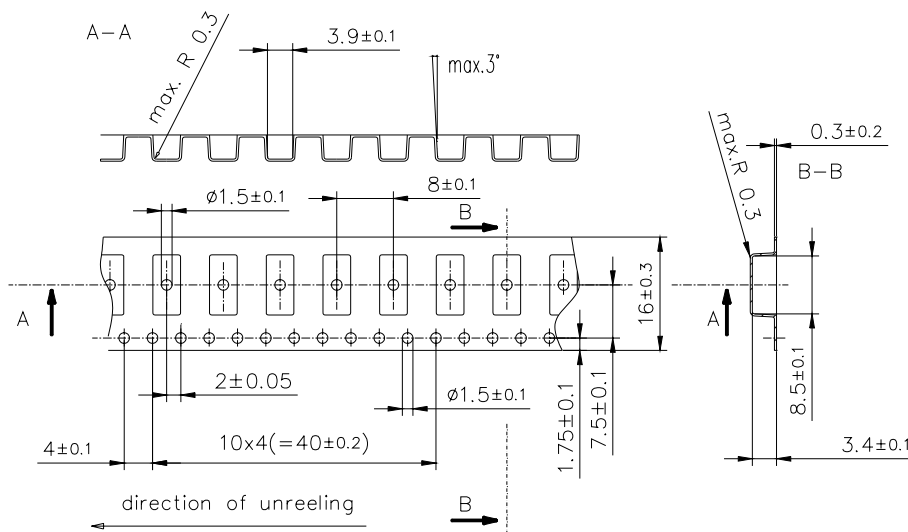
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	$^{\circ}\text{C}$ $^{\circ}\text{C}$

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 2000



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